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DERWENT-WEEK: 200235

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TITLE: Stacked BLP package and  
method for manufacturing the  
same

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PATENT-ASSIGNEE: HYNIX SEMICONDUCTOR INC [HYNIN]

PRIORITY-DATA: 1999KR-0068299 (December 31, 1999)

PATENT-FAMILY:

PUB-NO	PAGES	PUB-DATE
LANGUAGE		MAIN-IPC
KR 2001087444 A		September 21, 2001
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APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-
NO	APPL-DATE	
KR2001087444A	N/A	
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INT-CL (IPC): H01L023/12

ABSTRACTED-PUB-NO: KR2001087444A

BASIC-ABSTRACT:

NOVELTY - A stacked BLP package and a method for

manufacturing the same are provided to emit efficiently the heat generated from a package by installing a heat-sink on a semiconductor chip.

DETAILED DESCRIPTION - A multitude of chip pad(21a) is adhered to a semiconductor chip(21). A lead frame(22) for forming a lower lead(22a) and an upper lead(22b) is installed on the chip pads(21a). The lead frame(22) is connected electrically with the semiconductor chip(21) by a metal wire(23). A molding portion(24) is formed to expose a bottom portion of the semiconductor chip(21), a bottom portion of the lower lead(22a), and an upper portion of the upper lead(22b). A solder ball(24) is adhered to a bottom portion of the lower lead(22a). An epoxy(26) is formed on upper lead(22b). A heat-sink(27) is adhered to a bottom portion of the semiconductor chip(21).

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: STACK PACKAGE METHOD MANUFACTURE

DERWENT-CLASS: U11

EPI-CODES: U11-D01C6; U11-D02B2;

